



**China Semiconductor Industry Report,
2014-2015**

Jul. 2015

STUDY GOAL AND OBJECTIVES

This report provides the industry executives with strategically significant competitor information, analysis, insight and projection on the competitive pattern and key companies in the industry, crucial to the development and implementation of effective business, marketing and R&D programs.

REPORT OBJECTIVES

- ◆ To establish a comprehensive, factual, annually updated and cost-effective information base on market size, competition patterns, market segments, goals and strategies of the leading players in the market, reviews and forecasts.
- ◆ To assist potential market entrants in evaluating prospective acquisition and joint venture candidates.
- ◆ To complement the organizations' internal competitor information gathering efforts with strategic analysis, data interpretation and insight.
- ◆ To suggest for concerned investors in line with the current development of this industry as well as the development tendency.
- ◆ To help company to succeed in a competitive market, and

METHODOLOGY

Both primary and secondary research methodologies were used in preparing this study. Initially, a comprehensive and exhaustive search of the literature on this industry was conducted. These sources included related books and journals, trade literature, marketing literature, other product/promotional literature, annual reports, security analyst reports, and other publications. Subsequently, telephone interviews or email correspondence was conducted with marketing executives etc. Other sources included related magazines, academics, and consulting companies.

INFORMATION SOURCES

The primary information sources include Company Reports, and National Bureau of Statistics of China etc.

Abstract

According to China Semiconductor Industry Association, the total value of the entire semiconductor industry chain exceeded RMB300 billion in 2014, of which only RMB104.7 billion or one-third was concerned with products (excluding foreign companies). The IC export volume is still optimistic in a relative sense, but it is mostly contributed by foreign companies in China, rather than local enterprises.

Without foreign companies, Taiwanese enterprises and software business, Chinese semiconductor industry turns to be a real pattern like this: the output value of China semiconductor industry approximated USD12.5 billion in 2014, of which USD5 billion came from IC design, USD3.7 billion from IC fabrication, USD3.8 billion from IC packaging and testing. Apparently, IC design accounted for a higher proportion, in fact, the foundries of IC design companies mainly referred to Taiwanese TSMC or UMC, especially large IC design companies; about 80% of wafers were produced by Taiwanese TSMC. This means the irrelevance between IC design companies and foundries in Mainland China.

Since 2014, Chinese financial institutions or enterprises which are adept at capital operation and have huge capital have acquired semiconductor companies worldwide vigorously. China is trying to expand its semiconductor industry rapidly through acquisitions. However, the semiconductor industry requires long-term accumulation of talents and technologies, the semiconductor industry of China still has a long way to go even if it renders capital operation.

Chinese government makes great efforts to support the memory sector of the semiconductor industry with the investment of at least USD10 billion, because China is the largest memory market and buys 75% of the global memory. If the global memory industry structure remains stable, China will import tens of billions in USD of memory each year.

Most of Chinese IC design companies rely on their powerful parent companies which are partly state-owned enterprises with dominating positions and non-market-oriented operation to thrive and almost no independent IC design companies exist. For example, the parent company of Nari Smart-chip Microelectronics is a subsidiary of State Grid with main products -- smart meter IC and a monopoly position.

The parent company of CEC Huada is China Electronics Corporation (CEC) which monopolizes the ID card-use IC market. Non-state-owned large enterprises Huawei, ZTE, Datang Telecom (with TD-SCDMA technology) and SMIC Microelectronics act as the backers of Hisilicon, ZXIC, Leadcore Technology and Galaxycore respectively.

Independent IC design companies include Spreadtrum, RDA, Rockchip and Allwinner Technology. Spreadtrum and RDA which need a lot of money but hold limited financing channels have been acquired by state-owned enterprises. Major shareholders and technology sources of Goodix and FocalTech are actually Taiwanese companies.

In Mainland China, IC design companies are highly dependent on mobile phone and tablet PC markets. Some companies are even completely dependent on the smart card market, such as Nari Smart-chip Microelectronics, Fudan Microelectronics and Hua Hong Integrated Circuit.

Taiwanese IC design companies which are mostly independent firms are superior in technology to their counterparts in Mainland China; even if some Taiwanese companies relied on the parent companies at early stages, they have become dependent slowly, such as Himax and Novatek. Taiwanese IC design companies largely rely on the upstream industry chain instead of the downstream. Five of Taiwan's top 18 IC design companies focus on LCD driver because Taiwan's LCD panel industry ranks first in the world by shipment. In Chinese Mainland, IC design companies specialize in the digital field except RDA; in contrast, there are many Analog and Mixed IC design companies as well as two high-tech ASIC design companies of a certain scale in Taiwan.

The report covers the followings:

1. Global Semiconductor Market and Industry;
2. China Semiconductor Market and Industry;
3. Eleven Chinese IC Design Companies
4. Five Chinese Foundries
5. Four Chinese Packaging and Testing Companies

Ranking of Foundries in Mainland China, 2014 (Excluding Foreign and Taiwanese Companies)

Company	Revenue (USD mln)
SMIC	1,970
HHNEC	665
CSMC/ China Resources Microelectronics	318
Huali	296
Wuhan Xinxin	174
ASMC	132

Ranking of IC Design Companies in China, 2014

Company	Revenue (RMB bn)
Hisilicon	14.6
Spreadtrum	7.2
CEC Huada	3.2
Datang Semiconductor	3.1
ZXIC	3
Rockchip	2.8
Nari Smart-chip Microelectronics	2.5
RDA	2.2
Galaxycore	2
Allwinner Technology	1.2
GigaDevice	0.9
SMIC Microelectronics	0.6

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